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Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

Date: March 10, 2004

PATENT 36856.1170

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Eiichi NAGATSUKA et al.

Serial No.: 10/712,034

Filed: November 14, 2003

Title: RESISTANCE WELDING METHOD AND

STRUCTURE OF RESISTANCE WELDING PART,

AND METHOD FOR MANUFACTURING

ELECTRONIC COMPONENT AND ELECTRONIC

COMPONENT

Art Unit: 1725

Examiner: unknown

INFORMATION DISCLOSURE STATEMENT

Mail Stop DD Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Pursuant to 37 C.F.R. § 1.56, submitted herewith are copies of four (4) references cited in the enclosed Office Action issued in a corresponding Japanese Patent Application. For the Examiner's convenience, we have enclosed an English translation of the Japanese Office Action from the corresponding Japanese Patent Application and a completed Form PTO-1449.

The relevance of JP 63-165835 is set forth in the English translation of the Japanese Search Report attached hereto. Further, although the Japanese Search Report cites JP 3-258467, applicants did not include a copy of the reference herewith as U.S. Serial No. 10/712,034 March 10, 2004 Page 2 of 2

the reference has been previously cited in an Information Disclosure Statement filed on November 14, 2003.

The statement is not a representation that all of the information cited is necessarily effective as prior art against the application.

I hereby state that each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than 3 months prior to the filing of this statement, and that this is the first citation of these prior art references by a foreign patent office in a counterpart foreign patent application. Accordingly, no fee is necessary for the filing of this statement. Should the Commissioner determine otherwise, the Commissioner is authorized to charge Deposit Account No. 50-1353 for any fee shortages, including the petition fee under 37 C.F.R. § 1.17(p).

Applicants respectfully request that the disclosed references be made of record in the subject application.

Date: March 10, 2004

Attorneys for Applicant(s)

Joseph R. Keating Registration No. 37,368

Respectfully submitted,

Christopher A. Bennett Registration No. 46,710

KEATING & BENNETT LLP 10400 Eaton Place, Suite 312 Fairfax, VA 22030 (703) 385-5200

Dispatch Date: February 10, 2004

NOTIFICATION OF REASONS FOR REJECTION

Patent Application No.:

Patent Application No. 248164 of Heisei 11 [1999]

Draft Date:

January 30, 2004

Patent Office Examiner:

Toshiro Kanazawa

3117 3P00

Agent of Patent Applicant:

Masaaki Koshiba (and one other)

Applicable Sections:

Section 29 (2)

[Stamp: Received, 2/12/04, Koshiba Patent Office]

The present application should be rejected for the following reasons. If you have an opinion concerning this, please submit a statement of opinion within 60 days of the date of dispatch of this notification.

Reasons

The inventions claimed in the following claims of the present application are inventions that could easily have been invented prior to the filing of the application by a person having an ordinary knowledge of the technical field to which the inventions belong on the basis of inventions described in the following publications, which were disseminated in Japan or in foreign countries prior to the filing of the application. Thus, in accordance with the provisions of Section 29 (2) of the Patent Law, these inventions cannot be patented.

Note (For cited references, etc., see the Table of Cited References, etc.)

- Claims 1 through 3 and 5 through 10
- Cited References, etc. 1, 2, and 3
- Remarks:

In Cited Reference 1, see Claims 1 and 2, etc.

In Cited Reference 2, see Embodiment 1.

In Cited Reference 3, see the fact that metal gaps $[sic]^*$ 12 and 13 consisting of silver-plated iron and center conductors 8 consisting of phosphor bronze are resistance-welded.

No particular difference is recognized between the invention described in Cited Reference 1 or 2 and the inventions of Claims 1 through 3 and 5 of the present application.

The invention of Claim 6 of the present application specifies the thickness of the alloy layer, but the optimization of the numerical range of the thickness of the alloy layer is not recognized as something that goes beyond the ordinary creative ability range exhibited by a person skilled in the art.

A person skilled in the art could easily envision the use of nickel plating (Cited References 1

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^{*} Translator's note: apparent error in the original for "metal caps."

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Dispatch Date: February 10, 2004

and 2) that is universally known in the resistance welding of an iron-type alloy and a copper-type alloy, in place of silver plating described in Cited Reference 3, thus devising the inventions of Claims 7 through 10 of the present application.

- Claim 4
- Cited References, etc. 4 and 5
- Remarks:

In Cited Reference 4, see Claim 2.

In Cited Reference 5, see the description in line 5 of the upper-right section of page 2 to line 7 of the lower-right section of the same page.

It is recognized that the Fe-Sn-type alloy layer growth problem is also encountered in the invention described in Cited Reference 4, in which iron or an iron alloy is plated with tin. A person skilled in the art could envision without any particular difficulty the invention of Claim 4 of the present application by referring to the invention described in Cited Reference 5, which belongs to the same technical field of resistance welding and which suppresses the growth of an Fe-Sn-type alloy layer in the resistance welding using a nickel-plated underlying layer so that welding defects are not generated, and by adding a nickel-plated underlying layer.

Furthermore,

- 1) If amending the specification, underline the portions of the description where changes are made as a result of the amendment. (Regulation under the Patent Law, Format No. 13, Remark 6)
- 2) When making amendment(s), care should be taken not to add a new item, and the portions of the description constituting the grounds for the amendment(s) in the initial specification at the time of filing should be indicated in an Opinion Brief.

Table of Cited References, etc.

- 1. Japanese Patent Application Kokai No. H03-258467
- 2. Japanese Patent Application Kokai No. H02-256158
- 3. Microfilm of Japanese Utility Model Application No. S62-058143 (Japanese Utility Model Application Kokai No. S63-165835)
- 4. Japanese Patent Application Kokai No. H04-089180
- 5. Japanese Patent Application Kokai No. S57-023091

Record of Results of Survey of Prior Art References

B23K 11/12 IPC 7th Edition • Field surveyed:

Japanese Patent Application Kokai No. H04-251679 (Claim 5, • Prior Art References:

Table 4, etc.)

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This record of the results of a survey of prior art references does not constitute any reason for rejection.

If you have any inquiries regarding the content of this Notification of Reasons for Rejection, or if you wish to have an interview, please contact [the following person]:

Examination Department 2, Special Processing, Tatsushi Onoda TEL. 03 (3581) 1101, extension 3364

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N DISCLOSURE STATEMENT BY APPLICANT

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Sheet	1	of	1			

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	U.S. PATENT DOCUMENTS				
Examiner Initials*	Cite No. ¹	Document Number Number-Kind Code ^{2(if known)}	Publication Date MM -YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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		Country Code ³ -Number-Kind Code ⁵ (if known)	MM -YYYY		Figures Appear	
	1	JP 63-165835	10/1988			
	2	JP 2-256158	10/1990			X
	3	JP 4-89180	03/1992			X
	4	JP 57-23091	02/1982	Justin 19 1.		X
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Signature Considered	

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^{*}Examiner: Initial if reference considered, whether of not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered, include copy of this form with next communication to applicant.

Applicant unique citation designation number (optional). 2See Kind Codes of USPTO Patent documents at www.uspto.gov or MPEP 901.04. 3 Enter

Office that issued the document by the two-letter code (WIPO Strandard ST.3). 4 For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. 5 Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. 6 Applicant is to place a check mark here if English language Abstract is attached.

This collection of information is required by 37 CFR 1.97 and 1.98. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14.